

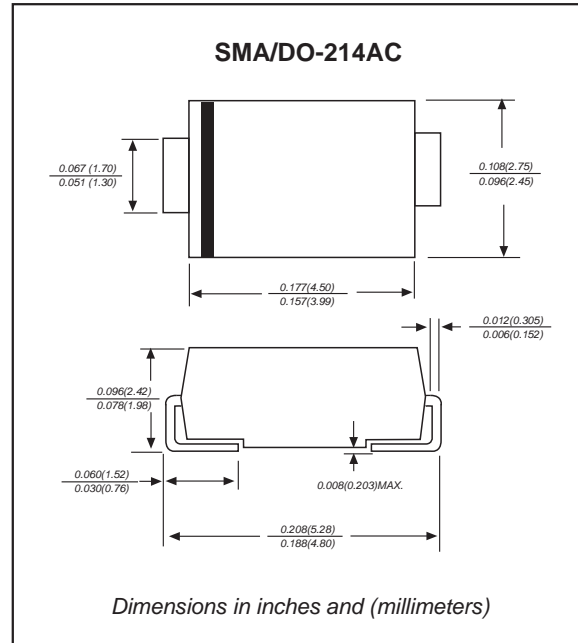
Features

- ▶ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ▶ For surface mounted applications
- ▶ Ultra fast switching for high efficiency
- ▶ Low reverse leakage
- ▶ Built-in strain relief, ideal for automated placement
- ▶ High forward surge current capability
- ▶ High temperature soldering guaranteed 260 C/10 seconds at terminals
- ▶ Glass passivated chip junction

Mechanical data

- ▶ **Case:** JEDEC SMA/DO-214AC molded plastic body
- ▶ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ▶ **Polarity:** Color band denotes cathode end
- ▶ **Mounting Position:** Any

Package outline

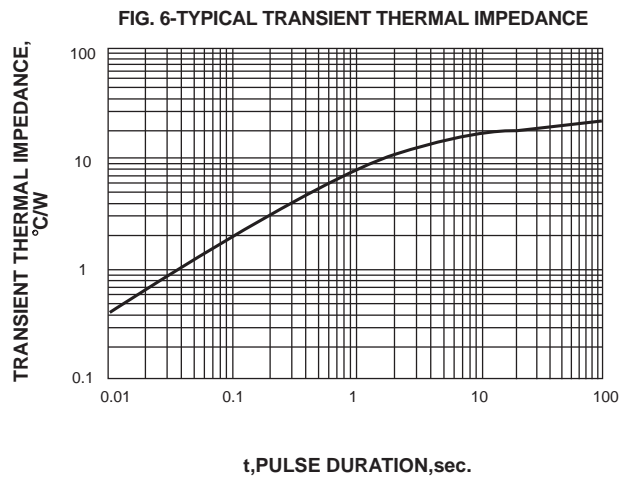
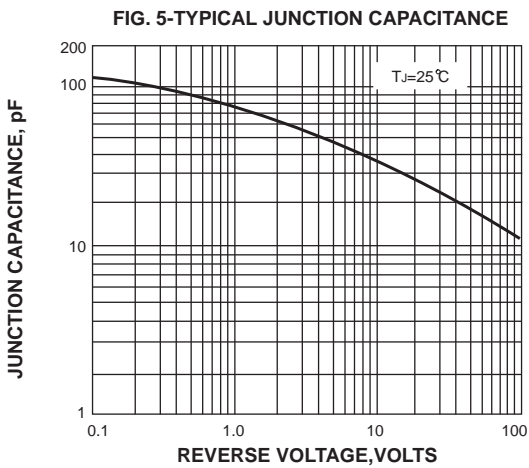
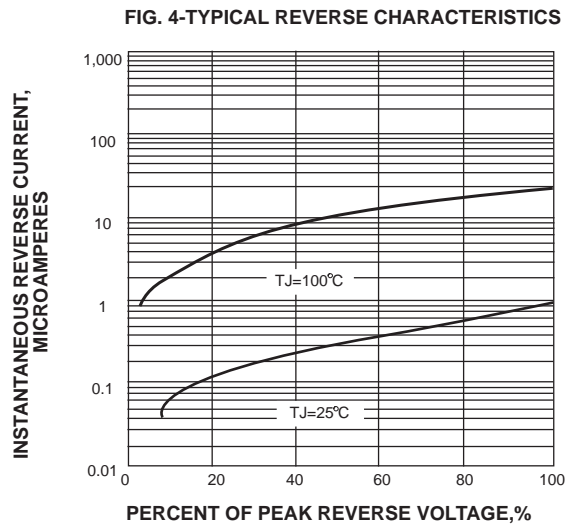
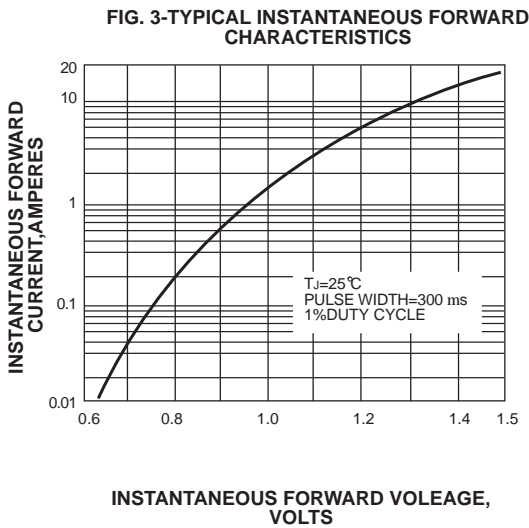
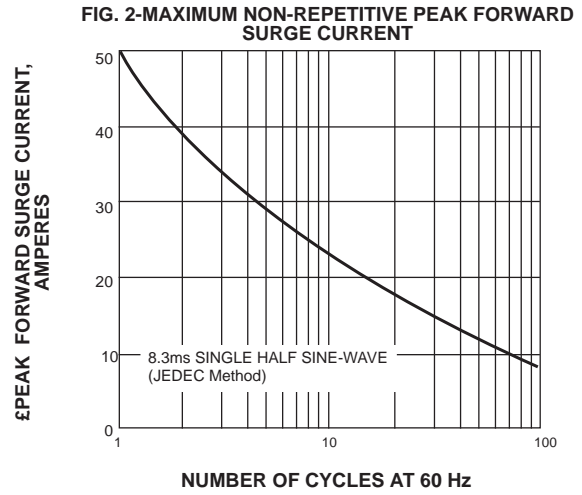
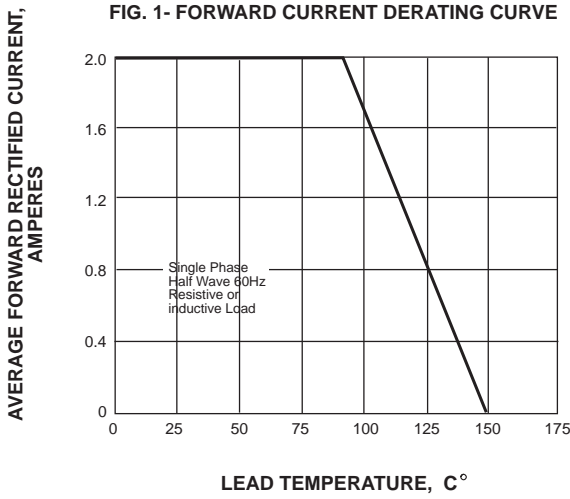


Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	RS2AA	RS2BA	RS2DA	RS2GA	RS2JA	RS2KA	RS2MA	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current 0.375" (9.5mm) lead length at $T_L=90^\circ\text{C}$	$I_{(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50.0							A
Maximum instantaneous forward voltage at 2.0A	V_F	1.3							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	I_R	5.0 50.0							μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	150			250	500		ns	
Typical junction capacitance (NOTE 2)	C_J	50.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	20.0							$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$

Note: 1.Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$
 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3.P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Rating and characteristic curves



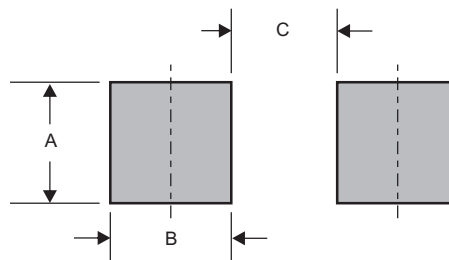
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
RS2AA	RS2A
RS2BA	RS2B
RS2DA	RS2D
RS2GA	RS2G
RS2JA	RS2J
RS2KA	RS2K
RS2MA	RS2M

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smin}) -Temperature Max(T _{smax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _p)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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